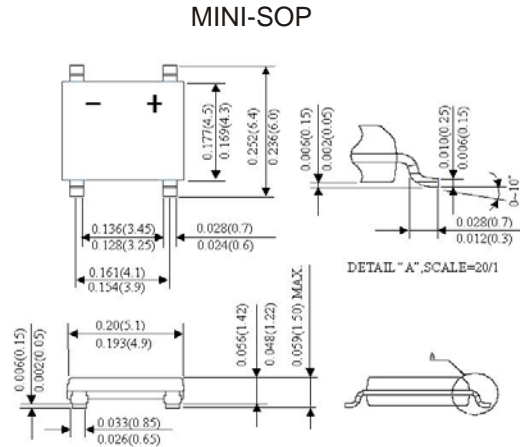


Features

- ✧ Glass passivated junction
- ✧ Ideal for printed circuit board
- ✧ Reliable low cost construction utilizing molded plastic technique
- ✧ High temperature soldering guaranteed:
260°C / 10 seconds / 0.375" (9.5mm)
lead length at 5 lbs., (2.3 kg) tension
- ✧ Small size, simple installation
Leads solderable per MIL-STD-202,
Method 208
- ✧ High surge current capability



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	LB2S	LB4S	LB6S	LB8S	LB10S	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	200	400	600	800	1000	V
Maximum Average Forward Rectified Current On glass-epoxy P.C.B. On aluminum substrate	$I_{(AV)}$	0.8 1.0					A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	30					A
Maximum Instantaneous Forward Voltage @ 0.4A	V_F	0.95					V
Maximum DC Reverse Current @ $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage	I_R	10					μA μA
Typical Thermal resistance Junction to Lead On aluminum substrate On Glass-Epoxy substrate	$R\theta_{JL}$ $R\theta_{JA}$	25 62.5 80					$^\circ\text{C}/\text{W}$
Operating Temperature Range	T_J	-55 to +150					$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150					$^\circ\text{C}$

RATINGS AND CHARACTERISTIC CURVES (ABS2 THRU ABS10)

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

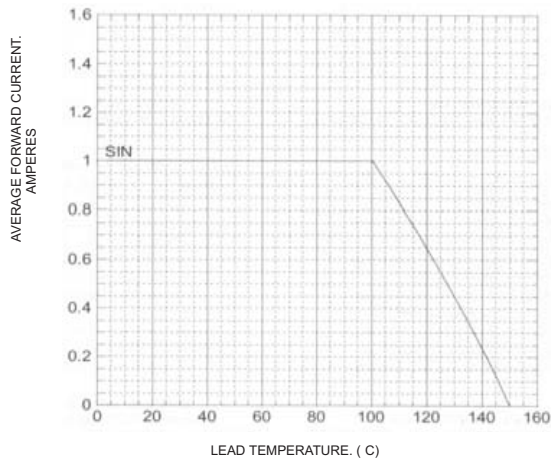


FIG.2- TYPICAL FORWARD CHARACTERISTICS

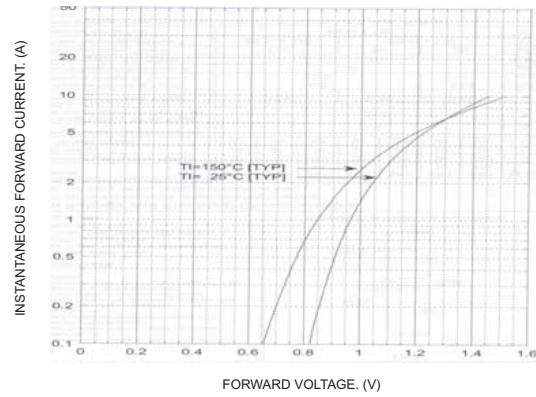


FIG.3- MAXIMUM FORWARD CURRENT DERATING CURVE

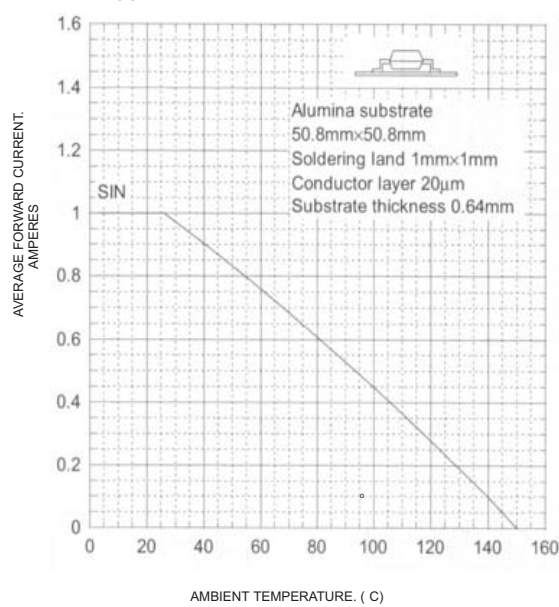


FIG.4- FORWARD POWER DISSIPATION

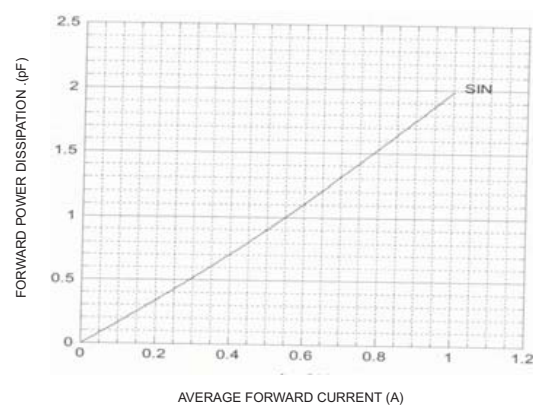


FIG.5- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

